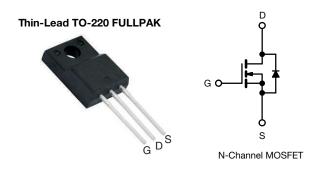
COMPLIANT

HALOGEN

**FREE** 



## **E Series Power MOSFET**



PRODUCT SUMMARY		
V <sub>DS</sub> (V) at T <sub>J</sub> max.	65	0
R <sub>DS(on)</sub> typ. (Ω) at 25 °C	V <sub>GS</sub> = 10 V	0.137
Q <sub>g</sub> max. (nC)	30	6
Q <sub>gs</sub> (nC)	10	0
Q <sub>gd</sub> (nC)	6	3
Configuration	Sin	gle

#### **FEATURES**

- 4<sup>th</sup> generation E series technology
- Low figure-of-merit (FOM) Ron x Qg
- Low effective capacitance (Co(er))
- · Reduced switching and conduction losses
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <a href="https://www.vishay.com/doc?99912"><u>www.vishay.com/doc?99912</u></a>

#### **APPLICATIONS**

- · Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
  - High-intensity discharge (HID)
  - Fluorescent ballast lighting
- Industrial
  - Welding
  - Induction heating
  - Motor drives
  - Battery chargers
  - Solar (PV inverters)

ORDERING INFORMATION	
Package	Thin-Lead TO-220 FULLPAK
Lead (Pb)-free and halogen-free	SiHA150N60E-GE3

PARAMETER			SYMBOL	LIMIT	UNIT
Drain-source voltage			$V_{DS}$	600	W
Gate-source voltage			$V_{GS}$	s ± 30	
Continuous dusin surrent /T 150 °C) 6	V <sub>GS</sub> at 10 V	$T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$	I-	9	
Continuous drain current (T <sub>J</sub> = 150 °C) <sup>e</sup>	VGS at 10 V	T <sub>C</sub> = 100 °C	ID	6	Α
Pulsed drain current <sup>a</sup>			I <sub>DM</sub>	43	
Linear derating factor				1.42	W/°C
Single pulse avalanche energy b		E <sub>AS</sub>	111	mJ	
Maximum power dissipation		P <sub>D</sub>	179	W	
Operating junction and storage temperature rai	nge		T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C
Drain-source voltage slope $T_J = 125 ^{\circ}\text{C}$		dv/dt	100	V/ns	
Reverse diode dv/dt <sup>d</sup>			dv/dt -	5	V/IIS
Mounting torque, M3 screw				0.6	Nm
Soldering recommendations (peak temperature) c For 10 s		For 10 s		260	°C

#### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b.  $V_{DD}$  = 120 V, starting  $T_J$  = 25 °C, L = 28.2 mH,  $R_g$  = 25  $\Omega$ ,  $I_{AS}$  = 2.8 A
- c. 1.6 mm from case
- d.  $I_{SD} \le I_D$ , di/dt = 100 A/ $\mu$ s, starting  $T_J$  = 25 °C
- e. Limited by maximum junction temperature



# Vishay Siliconix

THERMAL RESISTANCE RATI	NGS			
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum junction-to-ambient	$R_{thJA}$	-	65	°C/W
Maximum junction-to-case (drain)	$R_{thJC}$	-	3.8	C/VV

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static		-					
Drain-source breakdown voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		600	-	-	V
V <sub>DS</sub> temperature coefficient	$\Delta V_{DS}/T_{J}$	Referenc	e to 25 °C, I <sub>D</sub> = 1 mA	-	0.62	-	V/°C
Gate-source threshold voltage (N)	V <sub>GS(th)</sub>	V <sub>DS</sub> =	· V <sub>GS</sub> , I <sub>D</sub> = 250 μA	3.0	-	5.0	V
Onto anima lankana		,	$V_{GS} = \pm 20 \text{ V}$	-	-	± 100	nA
Gate-source leakage	$I_{GSS}$	,	$V_{GS} = \pm 30 \text{ V}$	-	-	± 1	μA
7		V <sub>DS</sub> =	600 V, V <sub>GS</sub> = 0 V	-	-	1	μΑ
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 480 V	, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C	-	-	10	
Drain-source on-state resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 10 A	-	0.137	0.158	Ω
Forward transconductance	9 <sub>fs</sub>	V <sub>DS</sub>	= 10 V, I <sub>D</sub> = 10 A	-	5.1	-	S
Dynamic							
Input capacitance	C <sub>iss</sub>	$V_{GS} = 0 \text{ V},$ $V_{DS} = 100 \text{ V},$ $f = 100 \text{ KHz}$		-	1514	-	pF
Output capacitance	C <sub>oss</sub>			-	60	-	
Reverse transfer capacitance	C <sub>rss</sub>			-	2	-	
Effective output capacitance, energy related	C <sub>o(er)</sub>	$V_{DS} = 0 \text{ V to } 400 \text{ V}, V_{GS} = 0 \text{ V}$		-	58	-	
Effective output capacitance, time related	C <sub>o(tr)</sub>			-	322	-	
Total gate charge	Qg			-	24	36	
Gate-source charge	Q <sub>gs</sub>	V <sub>GS</sub> = 10 V	$I_D = 10 \text{ A}, V_{DS} = 480 \text{ V}$	-	10	-	nC
Gate-drain charge	Q <sub>gd</sub>			-	6	-	
Turn-on delay time	t <sub>d(on)</sub>			-	20	40	
Rise time	t <sub>r</sub>	$V_{DD} = 480 \text{ V}, I_D = 10 \text{ A},$		-	27	54	
Turn-off delay time	t <sub>d(off)</sub>	V <sub>GS</sub> =	$V_{GS} = 10 \text{ V}, R_g = 9.1 \Omega$		28	56	ns -
Fall time	t <sub>f</sub>				17	34	
Gate input resistance	$R_g$	f = 1 MHz, open drain		0.4	0.9	1.8	Ω
<b>Drain-Source Body Diode Characteristic</b>	s						
Continuous source-drain diode current	I <sub>S</sub>	MOSFET symbol showing the integral reverse p - n junction diode		-	-	22	
Pulsed diode forward current	I <sub>SM</sub>			-	-	43	A A
Diode forward voltage	V <sub>SD</sub>	T <sub>J</sub> = 25 °C	C, I <sub>S</sub> = 10 A, V <sub>GS</sub> = 0 V	-	-	1.2	V
Reverse recovery time	t <sub>rr</sub>			-	291	582	ns
Reverse recovery charge	Q <sub>rr</sub>	T <sub>J</sub> = 25 °C, $I_F = I_S = 10 \text{ A}$ , di/dt = 100 A/ $\mu$ s, $V_R = 25 \text{ V}$		-	3.5	7.0	μC
Reverse recovery current	I <sub>RRM</sub>			_	21	-	A



### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

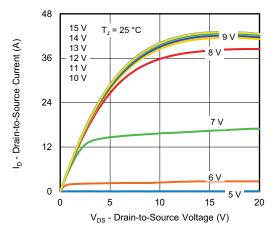


Fig. 1 - Typical Output Characteristics

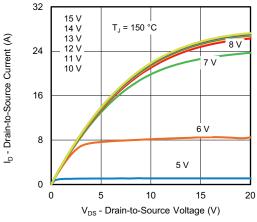


Fig. 2 - Typical Output Characteristics

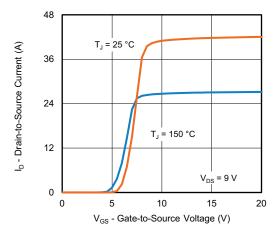


Fig. 3 - Typical Transfer Characteristics

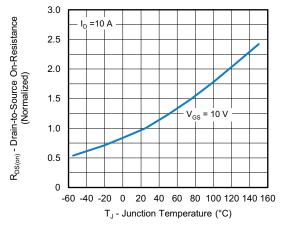


Fig. 4 - Normalized On-Resistance vs. Temperature

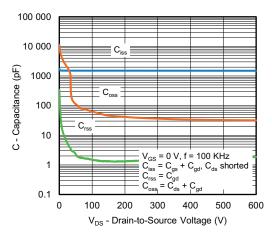


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

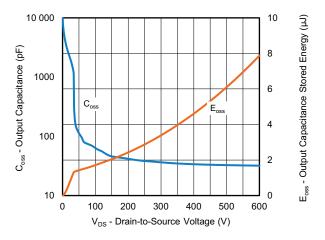


Fig. 6 - Coss and Eoss vs. VDS



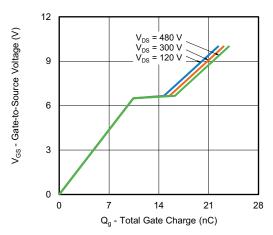


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

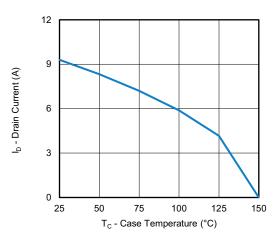


Fig. 9 - Maximum Drain Current vs. Case Temperature

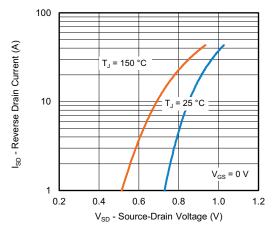


Fig. 8 - Typical Source-Drain Diode Forward Voltage

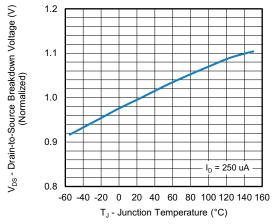


Fig. 10 - Temperature vs. Drain-to-Source Voltage

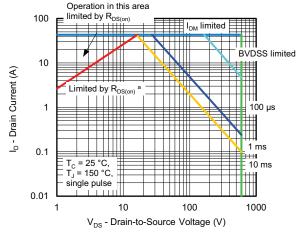


Fig. 11 - Maximum Safe Operating Area

#### Note

a.  $V_{GS}$  > minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified



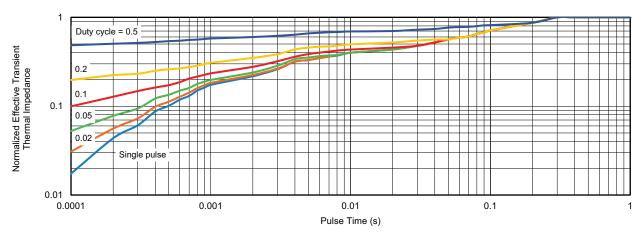


Fig. 12 - Normalized Transient Thermal Impedance, Junction-to-Case

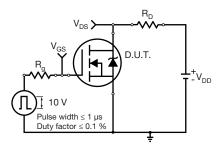


Fig. 13 - Switching Time Test Circuit

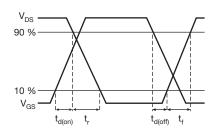


Fig. 14 - Switching Time Waveforms

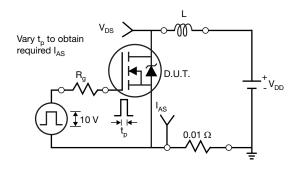


Fig. 15 - Unclamped Inductive Test Circuit

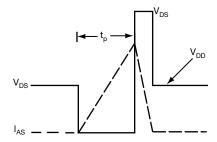


Fig. 16 - Unclamped Inductive Waveforms

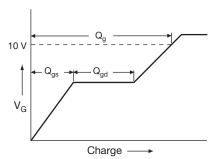


Fig. 17 - Basic Gate Charge Waveform

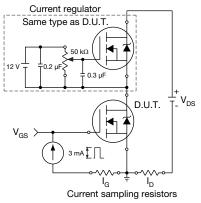
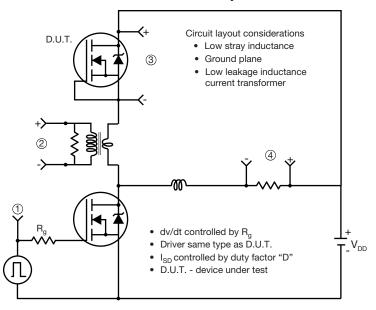


Fig. 18 - Gate Charge Test Circuit



#### Peak Diode Recovery dv/dt Test Circuit



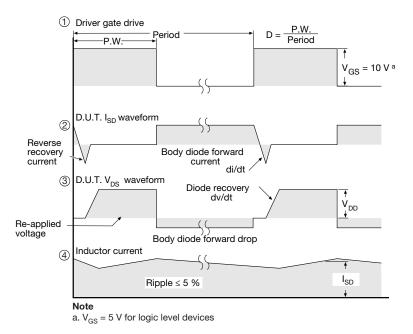
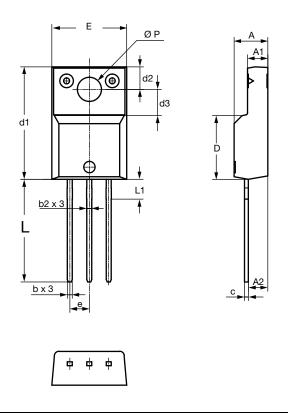


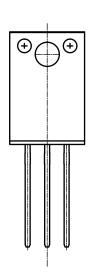
Fig. 19 - For N-Channel

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# **TO-220 FULLPAK Thin Lead**





SYMBOL	DIMENSIONS				
	MILLIN	IETERS	INCHES		
	MIN.	MAX.	MIN.	MAX.	
А	4.30	4.70	0.169	0.185	
A1	2.50	2.90	0.098	0.114	
A2	2.40	2.80	0.094	0.110	
b	0.60	0.80	0.024	0.031	
b2	0.60	0.90	0.024	0.035	
С	-	0.60	-	0.024	
D	8.30	8.70	0.327	0.342	
d1	14.70	15.30	0.579	0.602	
d2	2.90	3.10	0.114	0.122	
d3	3.30	3.70	0.130	0.146	
Е	9.70	10.30	0.382	0.406	
е	2.50	2.70	0.098	0.106	
L	13.40	13.80	0.528	0.543	
L1	1.00	2.80	0.039	0.110	
ØP	3.00	3.40	0.118	0.134	

ECN: E20-0684-Rev. D, 28-Dec-2020

DWG: 6021



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